

Electronic Patent Application Fee Transmittal

Application Number:	10668914			
Filing Date:	23-Sep-2003			
Title of Invention:	PROCESS AND INTEGRATION SCHEME FOR FABRICATING CONDUCTIVE COMPONENTS, THROUGH-VIAS AND SEMICONDUCTOR COMPONENTS INCLUDING CONDUCTIVE THROUGH-WAFER VIAS			
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Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
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Miscellaneous-Filing:				
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Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
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